	© Copyright 2005. If CONNECTING INDUSTRIES® international and Pan	PC, Bannockb	ourn, Illinois. A	Il rights reserved u ntions.	nder both	This docume level parts, t	ent is a declaration	tion of the encomp	he substances asses all low	s within the er level mat	manufactur erials for wl	er listed it hich the m	tem. Note:	if the item is an as or has engineering	sembly with low responsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information					
upplier	Information														
Company name* Company unique				que ID [Unique ID Authority					Response Date*			
nsemi												2024-05-04			
ontact Na	ame		Title - Contact			1	Phone - Contact*				Email - Contact*				
roduct-E	nv-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized	Representative*		Title - Representative]	Phone - Representative*				Email - Representative*				
roduct-E	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Date	e Vers	Version Manufacturing Site		1	Weight*	UOM	Unit Type	
	IN4001RLG REC AXIA		REC AXIAL 1A	1A 50V STD TR		2024-05-04			CNP		2	250.82	mg	Each	
Ianufac	turing Proccess Informat	tion												·	
,	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperat		ure Max Time at Peak Tem		Temperat	ure Num	ber of Reflow Cyc	les		
Matte Tin (Sn) - annealed			CU Alloy NA				0 C 30			seconds 3					
omments															
or more in	nformation regarding material	composition :	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed								
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.18	mg	Supplier	Silicon (Si)	7440-21-3		0.18	mg
Die Attach Solder	7.98	mg	Supplier	Silver (Ag)	7440-22-4		0.1995	mg
			А	Lead (Pb)	7439-92-1	7a	7.3815	mg
			Supplier	Tin (Sn)	7440-31-5		0.399	mg
Lead Frame	125.08	mg	Supplier	Copper (Cu)	7440-50-8		125.08	mg
Mold Compound-Black	116.8	mg		Metal Hydroxide	proprietary data		5.84	mg
			Supplier	Carbon Black (C)	1333-86-4		1.168	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		87.6	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		11.68	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		10.512	mg
Plating	0.78	mg	Supplier	Tin (Sn)	7440-31-5		0.78	mg